

## S-82H4 Series

## BATTERY PROTECTION IC FOR 3-SERIAL OR 4-SERIAL CELL PACK WITH CONSTANT VOLTAGE OUTPUT PIN FOR REAL-TIME CLOCK (SECONDARY PROTECTION)

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This IC is used for secondary protection of lithium-ion rechargeable batteries, and incorporates high-accuracy voltage detection circuits and delay circuits.

Short-circuiting between the VC1 and VC2 pins makes it possible to serially connect three cells.

Since this IC also comes with a constant voltage output circuit, it can be used as a constant-voltage power supply for an external RTC (Real-Time clock IC).

#### **■** Features

• High-accuracy voltage detection circuit for each cell

Overcharge detection voltage n 3.600 V to 4.800 V (5 mV step) Accuracy  $\pm 15 \text{ mV}$  (Ta =  $+25^{\circ}$ C)

Accuracy  $\pm 25$  mV (Ta =  $-10^{\circ}$ C to  $+60^{\circ}$ C)

Overcharge release voltage  $n^{*1}$  3.600 V to 4.800 V Accuracy  $\pm 50$  mV VRTC pin shutdown voltage n 2.500 V to 2.800 V (100 mV step) Accuracy  $\pm 50$  mV

Delay times for overcharge detection are generated only by an internal circuit (external capacitors are unnecessary)

Overcharge detection delay time, VRTC pin shutdown delay time: 1 s, 2 s, 4 s, 6 s

Overcharge timer reset function:
 Available, unavailable

• CO pin output voltage is limited to 7.5 V max.

• VRTC pin output voltage: 1.800 V to 3.300 V (100 mV step) Accuracy ±2% (Ta = +25°C)

• VRTC pin output current: 2 mA max.

• Wide operation temperature range: Ta =  $-40^{\circ}$ C to  $+85^{\circ}$ C

Low current consumption

During operation ( $V_{CU} - 1.0 \text{ V}$  for each cell): 4.0  $\mu$ A max. During VRTC pin shutdown ( $V_{RSD} - 1.0 \text{ V}$  for each cell): 1.0  $\mu$ A max.

• Lead-free (Sn 100%), halogen-free

\*1. Overcharge release voltage = Overcharge detection voltage – Overcharge hysteresis voltage (Overcharge hysteresis voltage can be selected from a range of 0 mV to 400 mV in 50 mV step.)

**Remark** 1. The order of battery connection of this IC is limited. Customers who desire a product that does not limit the order of battery connection should consider the S-82K3/K4 Series of products instead.

**2.** n = 1, 2, 3, 4

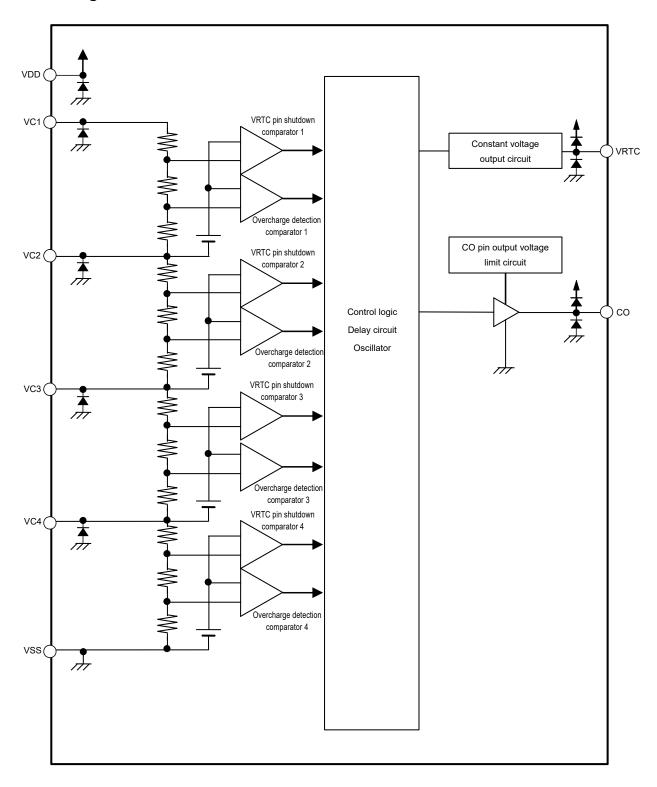
#### ■ Application

· Lithium-ion rechargeable battery packs (for secondary protection)

#### ■ Packages

- DFN-8(2020)A
- HSNT-8(1616)

## **■** Block Diagrams

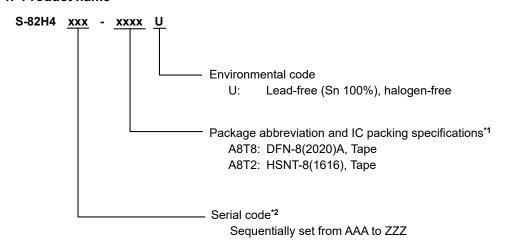


**Remark** Diodes in the figure are parasitic diodes.

Figure 1

#### **■ Product Name Structure**

#### 1. Product name



- \*1. Refer to the tape drawing.
- \*2. Refer to "3. Product name list".

#### 2. Packages

**Table 1 Package Drawing Codes** 

Package Name	Dimension	Tape	Reel	Land
DFN-8(2020)A	IB008-A-P-SD	IB008-A-C-SD	IB008-A-R-SD	IB008-A-L-SD
HSNT-8(1616)	PY008-A-P-SD	PY008-A-C-SD	PY008-A-R-SD	PY008-A-L-SD

#### 3. Product name list

#### 3. 1 DFN-8(2020)A

Table 2

				I UDIO E				
	Overcharge	Overcharge	VRTC Pin	VRTC Pin	VRTC Pin	Overcharge	VRTC Pin	Overcharge
Product Name	Detection	Release	Output	Shutdown	Recovery	Detection	Shutdown	Timer
Product Name	Voltage	Voltage	Voltage	Voltage	Voltage	Delay Time*1	Delay Time*1	Reset
	[Vcu]	[VcL]	[V <sub>VRTC</sub> ]	[V <sub>RSD</sub> ]	[V <sub>RST</sub> ]	[tcu]	[t <sub>RSD</sub> ]	Function*2
S-82H4AAA-A8T8U	4.600 V	4.300 V	3.300 V	2.500 V	2.700 V	6 s	6 s	Unavailable
S-82H4AAB-A8T8U	4.600 V	4.300 V	3.000 V	2.500 V	2.700 V	6 s	6 s	Unavailable
S-82H4AAC-A8T8U	4.650 V	4.350 V	3.300 V	2.500 V	2.700 V	6 s	6 s	Unavailable
S-82H4AAD-A8T8U	4.650 V	4.350 V	3.000 V	2.500 V	2.700 V	6 s	6 s	Unavailable
S-82H4AAE-A8T8U	4.550 V	4.300 V	3.300 V	2.500 V	2.700 V	6 s	6 s	Unavailable

<sup>\*1.</sup> Overcharge detection delay time, VRTC pin shutdown delay time:

1 s, 2 s, 4 s, 6 s

\*2. Overcharge timer reset function:

Available, unavailable

**Remark** Please contact our sales representatives for products other than the above.

#### 3. 2 HSNT-8(1616)

#### Table 3

Product Name	Overcharge	Overcharge	VRTC Pin	VRTC Pin	VRTC Pin	Overcharge	VRTC Pin	Overcharge
	Detection	Release	Output	Shutdown	Recovery	Detection	Shutdown	Timer
Product Name	Voltage	Voltage	Voltage	Voltage	Voltage	Delay Time*1	Delay Time*1	Reset
	[Vcu]	[VcL]	[V <sub>VRTC</sub> ]	[V <sub>RSD</sub> ]	[V <sub>RST</sub> ]	[tcu]	[t <sub>RSD</sub> ]	Function*2
S-82H4AAA-A8T2U	4.600 V	4.300 V	3.300 V	2.500 V	2.700 V	6 s	6 s	Unavailable

**<sup>\*1.</sup>** Overcharge detection delay time, VRTC pin shutdown delay time:

Available, unavailable

**Remark** Please contact our sales representatives for products other than the above.

<sup>1</sup> s, 2 s, 4 s, 6 s

<sup>\*2.</sup> Overcharge timer reset function:

## **■** Pin Configuration

#### 1. DFN-8(2020)A

Top view



Bottom view



Figure 2

Table 4

Pin No.	Symbol	Description
1	VDD	Positive power supply input pin
2	VC1	Positive power supply input pin Positive voltage connection pin of battery 1
3	VC2	Negative voltage connection pin of battery 1 Positive voltage connection pin of battery 2
4	VC3	Negative voltage connection pin of battery 2 Positive voltage connection pin of battery 3
5	VC4	Negative voltage connection pin of battery 3 Positive voltage connection pin of battery 4
6	VSS	Negative power supply input pin Negative voltage connection pin of battery 4
7	СО	FET gate connection pin for charge control
8	VRTC	Voltage output pin for Real-time Clock (RTC)

\*1. Connect the heat sink of backside at shadowed area to the board, and set electric potential open or V<sub>C1</sub>. However, do not use it as the function of electrode.

#### 2. HSNT-8(1616)

Top view



Bottom view



Figure 3

#### Table 5

Pin No.	Symbol	Description			
1	VDD	Positive power supply input pin			
2	VC1	Positive power supply input pin			
	VCI	Positive voltage connection pin of battery 1			
3	VC2	Negative voltage connection pin of battery 1			
3	VCZ	Positive voltage connection pin of battery 2			
4	VC3	Negative voltage connection pin of battery 2			
4	VC3	Positive voltage connection pin of battery 3			
5	VC4	Negative voltage connection pin of battery 3			
3	VC4	Positive voltage connection pin of battery 4			
6	VSS	Negative power supply input pin			
0	voo	Negative voltage connection pin of battery 4			
7	СО	FET gate connection pin for charge control			
8	VRTC	Voltage output pin for Real-time Clock (RTC)			

\*1. Connect the heat sink of backside at shadowed area to the board, and set electric potential open or V<sub>C1</sub>. However, do not use it as the function of electrode.

#### ■ Absolute Maximum Ratings

Table 6

(Ta = +25°C unless otherwise specified)

Item	Symbol	Applied Pin	Absolute Maximum Rating	Unit
Input voltage between VDD pin and VSS pin	V <sub>DS1</sub>	VDD	$V_{SS} - 0.3$ to $V_{SS} + 28$	V
Input voltage between VC1 pin and VSS pin	V <sub>DS2</sub>	VC1	$V_{SS} - 0.3$ to $V_{SS} + 28$	V
Input pin voltage	V <sub>IN</sub>	VC2, VC3, VC4	$V_{SS}-0.3$ to $V_{VC1}+0.3$	V
CO pin output voltage	V <sub>CO</sub>	CO	$V_{SS} - 0.3 \text{ to } V_{DD} + 0.3$	V
VRTC pin output voltage	V <sub>VRTC</sub>	VRTC	$V_{SS}-0.3$ to $V_{SS}+6$	V
Operation ambient temperature	T <sub>opr</sub>	-	−40 to +85	°C
Storage temperature	T <sub>stg</sub>	_	-40 to +125	°C

Caution The absolute maximum ratings are rated values exceeding which the product could suffer physical damage. These values must therefore not be exceeded under any conditions.

#### **■** Thermal Resistance Value

Table 7

		1 4 5 10 1					
Item	Symbol	Condition		Min.	Тур.	Max.	Unit
			Board A	_	242	_	°C/W
			Board B	_	182	1	°C/W
		DFN-8(2020)A	Board C	_	1	Ī	°C/W
	θја		Board D	_	ı	ı	°C/W
lumation to anchient the annual resistance*1			Board E	_	1	Ī	°C/W
Junction-to-ambient thermal resistance*1		HSNT-8(1616)	Board A	_	214	ı	°C/W
			Board B	_	172	Ī	°C/W
			Board C	_	ı	ı	°C/W
			Board D	_	1	1	°C/W
			Board E	_	_	_	°C/W

<sup>\*1.</sup> Test environment: compliance with JEDEC STANDARD JESD51-2A

**Remark** Refer to "■ **Power Dissipation**" and "**Test Board**" for details.

#### **■** Electrical Characteristics

Table 8

(Ta =  $+25^{\circ}$ C unless otherwise specified)

		_	(1a - 1	-23 C ui	ness otner	MISC S	occincu)
Item	Symbol	Condition	Min.	Тур.	Max.	Unit	Test Circuit
Detection Voltage							
Overcharge detection voltage n	Vcun	Ta = +25°C	V <sub>CU</sub> - 0.015	Vcu	V <sub>CU</sub> + 0.015	V	1
(n = 1, 2, 3, 4)	<b>v</b> Cun	Ta = $-10^{\circ}$ C to $+60^{\circ}$ C*1	V <sub>CU</sub> - 0.020	Vcu	V <sub>CU</sub> + 0.020	V	1
Overcharge release voltage n (n = 1, 2, 3, 4)	V <sub>CLn</sub>	-	V <sub>CL</sub> - 0.050	VcL	V <sub>CL</sub> + 0.050	V	1
VRTC pin shutdown voltage n (n = 1, 2, 3, 4)	V <sub>RSDn</sub>	-	V <sub>RSD</sub> - 0.050	V <sub>RSD</sub>	V <sub>RSD</sub> + 0.050	V	2
VRTC pin recovery voltage n (n = 1, 2, 3, 4)	V <sub>RSTn</sub>	-	V <sub>RST</sub> – 0.100	V <sub>RST</sub>	V <sub>RST</sub> + 0.100	V	2
Input Voltage							
Operation voltage between VDD pin and VSS pin	VDSOP	-	3.6	-	24	V	-
Output Voltage							
CO pin output voltage "H"	Vсон	_	4.0	6.0	7.5	V	2
Input Current			_			_	
Current consumption during operation	IOPE	V1 = V2 = V3 = V4 = V <sub>CU</sub> - 1.0 V	_	2.0	4.0	μΑ	2
Current consumption during VRTC pin shutdown	IOPED	V1 = V2 = V3 = V4 = V <sub>RSD</sub> - 1.0 V	-	_	1.0	μΑ	2
VC1 pin input current	I <sub>VC1</sub>	V1 = V2 = V3 = V4 = V <sub>CU</sub> - 1.0 V	_	_	3.7	μА	2
VCn pin input current (n = 2, 3, 4)	Ivcn	V1 = V2 = V3 = V4 = V <sub>CU</sub> - 1.0 V	-0.42	0	_	μA	2
Output Current							
CO pin source current	Ісон	_	_	_	-20	μΑ	2
CO pin sink current	Icol	_	20	_	_	μΑ	2
Delay Time							
Overcharge detection delay time	tcu	_	$t_{\text{CU}} \times 0.7$	tcu	t <sub>CU</sub> ×1.3	S	2
Overcharge release delay time	t <sub>CL</sub>	_	8	16	32	ms	2
Overcharge timer reset delay time	t <sub>TR</sub>	With overcharge timer reset function	6	12	20	ms	-
Transition time to test mode	t <sub>TST</sub>	-	_	_	10	ms	_
VRTC pin shutdown delay time	t <sub>RSD</sub>	-	$t_{\text{RSD}} \times 0.7$	t <sub>RSD</sub>	$t_{\text{RSD}} \times 1.3$	s	2
VRTC Pin Output	•	•		-			
VRTC pin output voltage	VVRTC	I <sub>VRTC</sub> = 10 μA, SW2 = ON	V <sub>VRTC</sub> × 0.98	VVRTC	V <sub>VRTC</sub> × 1.02	V	2
VRTC pin output current	Ivrtc	-	_	_	2	mA	_
	•	•			•		

**<sup>\*1.</sup>** Since products are not screened at high and low temperature, the specification for this temperature range is guaranteed by design, not tested in production.

#### **■** Test Circuit

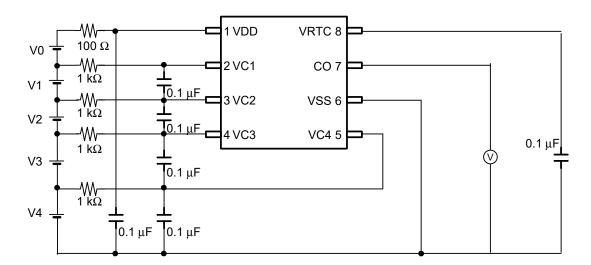


Figure 4 Test Circuit 1

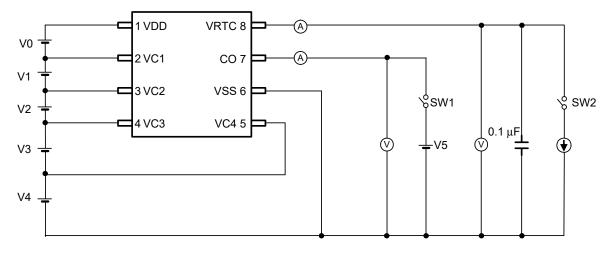


Figure 5 Test Circuit 2

In the initial status of the test circuit, SW1 and SW2 should be OFF.

This section provides explanations of test items using test circuit 1 and test circuit 2.

# 1. Overcharge detection voltage n ( $V_{\text{CUn}}$ ), overcharge release voltage n ( $V_{\text{CLn}}$ ) (Test Circuit 1)

After setting V0 = 0 V, V1 = V2 = V3 = V4 =  $V_{CU} - 0.1$  V, V1 is gradually increased. When the CO pin output inverts, the voltage V1 is defined as the overcharge detection voltage 1 ( $V_{CU1}$ ). After that, V1 is then set to  $V_{CU} + 0.1$  V, V2 = V3 = V4 = 3.5 V. V1 is gradually decreased. When the CO pin output inverts again, the voltage V1 is defined as the overcharge release voltage ( $V_{CL1}$ ).

Overcharge detection voltage n ( $V_{CUn}$ ) and overcharge release voltage n ( $V_{CLn}$ ) can be determined in the same way as when n = 1.

# 2. VRTC pin shutdown voltage n (V<sub>RSDn</sub>), VRTC pin recovery voltage n (V<sub>RSTn</sub>) (Test Circuit 2)

After setting V0 = 0 V, V1 = V2 = V3 = V4 = 3.5 V, V1 is gradually decreased. When the VRTC pin output becomes  $V_{SS}$ , the voltage V1 is defined as the VRTC pin shutdown voltage 1 ( $V_{RSD1}$ ). After that, V1 is then set to  $V_{RSD}$  – 0.15 V, V2 = V3 = V4 = 3.5 V. V1 is gradually increased. When the VRTC pin output voltage becomes the VRTC pin output voltage ( $V_{VRTC}$ ), the voltage V1 is defined as the VRTC pin recovery voltage 1 ( $V_{RST1}$ ).

VRTC pin shutdown voltage n (V<sub>RSDn</sub>) and VRTC pin recovery voltage n (V<sub>RSTn</sub>) can be determined in the same way as when n = 1.

## 3. CO pin output voltage "H" (V<sub>COH</sub>) (Test Circuit 2)

The CO pin output voltage "H" ( $V_{COH}$ ) is the voltage between the CO pin and the VSS pin when  $V_0 = 0$  V,  $V_1 = 4.9$  V,  $V_2 = V_3 = V_4 = 3.5$  V.

## 4. CO pin source current (I<sub>COH</sub>)

(Test Circuit 2)

Set SW1 to ON after setting V0 = 0 V, V1 = 4.9 V, V2 = V3 = V4 = 3.5 V, V5 =  $\text{V}_{\text{COH}} - 0.5 \text{ V}$ . The CO pin current is the CO pin source current ( $\text{I}_{\text{COH}}$ ) at that time.

# 5. CO pin sink current (I<sub>COL</sub>) (Test Circuit 2)

Set SW1 to ON after setting V0 = 0 V, V1 = V2 = V3 = V4 = 3.5 V, V5 = 0.5 V. The CO pin current is the CO pin sink current (I<sub>COL</sub>) at that time.

## 6. Overcharge detection delay time (tcu), overcharge release delay time (tcl) (Test Circuit 2)

After setting V0 = 0 V, V1 = V2 = V3 = V4 = 3.5 V, V1 is increased to 4.9 V. The overcharge detection delay time (t<sub>CU</sub>) is the time period until the CO pin output inverts. After that, decrease V1 to 3.5 V. The overcharge release delay time (t<sub>CL</sub>) is the time period until the CO pin output inverts.

# 7. VRTC pin shutdown delay time (t<sub>RSD</sub>) (Test Circuit 2)

After setting V0 = 0 V, V1 = V2 = V3 = V4 = 3.5 V, V1 is decreased to 2.4 V. The VRTC pin shutdown delay time ( $t_{RSD}$ ) is the time period until the VRTC pin output becomes Vss.

#### Operation

Remark Refer to "■ Battery Protection IC Connection Examples".

#### 1. Normal status

When all battery voltages are higher than the VRTC pin shutdown voltage ( $V_{RSDn}$ ) but lower than overcharge detection voltage n ( $V_{CUn}$ ), the CO pin outputs "L" and the VRTC pin outputs the VRTC pin output voltage ( $V_{VRTC}$ ). This status is called the normal status.

#### 2. Overcharge status

When the voltage of any of all batteries exceeds the overcharge detection voltage n (V<sub>CUn</sub>) and this condition continues for the overcharge detection delay time (t<sub>CU</sub>) or longer, the CO pin output inverts. This status is called the overcharge status. Charge control and secondary protection can be enabled by connecting an FET to the CO pin.

When all battery voltages fall below the overcharge release voltage ( $V_{CLn}$ ) and this condition continues for the overcharge release delay time ( $t_{CL}$ ) or longer, this IC returns to the normal status.

#### 3. VRTC pin shutdown status

When the voltage of any of the batteries falls below the VRTC pin shutdown voltage n ( $V_{RSDn}$ ) and this condition continues for the VRTC pin shutdown delay time ( $t_{RSD}$ ) or longer, the VRTC pin output becomes  $V_{SS}$ . This status is called the VRTC pin shutdown status.

When all battery voltages exceed the VRTC pin recovery voltage n (VRSTn), this IC returns to the normal status.

#### 4. Overcharge timer reset function

During  $t_{CU}$ , which is from when the voltage of any of the batteries being charged exceeds  $V_{CUn}$  until charging stops, this IC has the following operations.

Even if an overcharge release noise, which temporarily forces the battery voltage below  $V_{\text{CUn}}$ , is input,  $t_{\text{CU}}$  is continuously counted as long as the overcharge release noise time is shorter than the overcharge timer reset delay time  $(t_{\text{TR}})$ . Under the same conditions, if the overcharge release noise time is  $t_{\text{TR}}$  or longer, counting of  $t_{\text{CU}}$  is reset once. After that, when  $V_{\text{CUn}}$  has been exceeded, counting of  $t_{\text{CU}}$  resumes.

#### 5. Test mode

In this IC, the overcharge detection delay time ( $t_{CU}$ ) and VRTC pin shutdown delay time ( $t_{RSD}$ ) can be shortened by entering the test mode.

The test mode can be set by retaining the VDD pin voltage 7.0 V or higher than the VC1 pin voltage for at least 10 ms (V1 = V2 = V3 = V4 = 3.5 V, Ta = +25°C). The status is retained by the internal latch and the test mode is retained even if the VDD pin voltage is decreased to the same voltage as that of the VC1 pin.

When this IC becomes the detection status after the delay time following the detection of an overcharge or VRTC pin shutdown has elapsed, the latch for retaining the test mode is reset and this IC is released from the test mode.

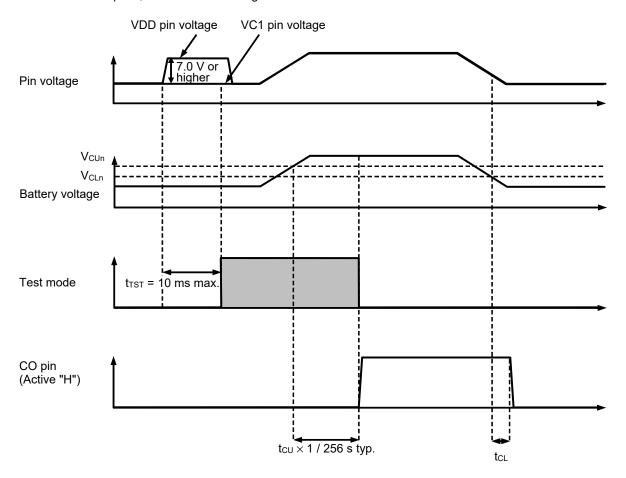


Figure 6

Caution 1. Set the test mode when no batteries are overcharged.

2. The overcharge timer reset delay time  $(t_{TR})$  is not shortened in the test mode.

## **■** Timing Charts

1. Overcharge detection operation (With overcharge timer reset function)

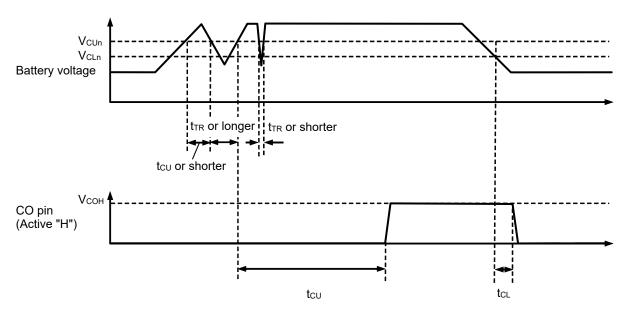


Figure 7

#### 2. VRTC pin shutdown operation

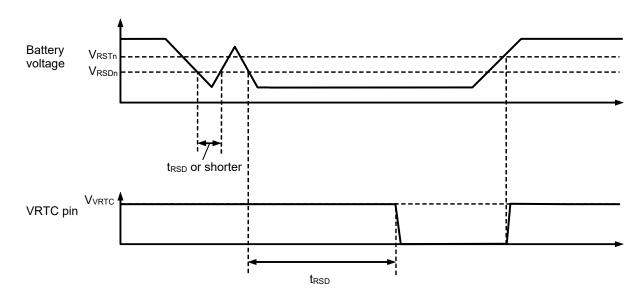


Figure 8

#### 3. Overcharge timer reset operation (With overcharge timer reset function)

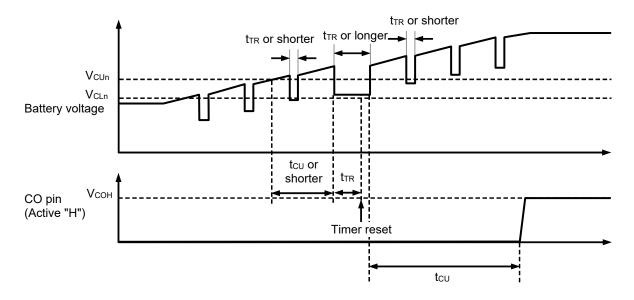
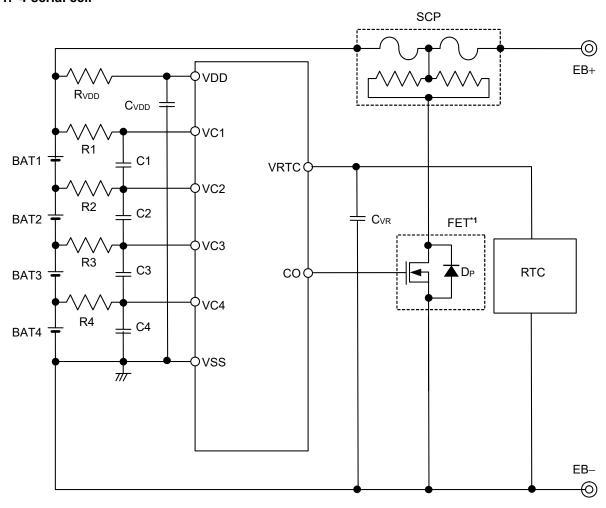


Figure 9

#### ■ Battery Protection IC Connection Examples

#### 1. 4-serial cell



**\*1.** This IC limits its CO pin output voltage to 7.5 V max., so a FET with the gate withstand voltage of 8 V can be used.

Figure 10

**Table 9 Constants for External Components** 

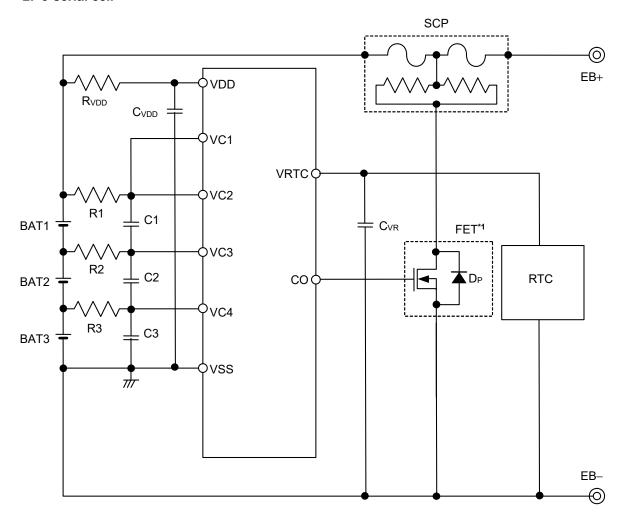
No.	Part	Min.	Typ.*1	Max.	Unit
1	R1 to R4	1	1	1	kΩ
2	C1 to C4, C <sub>VDD</sub>	0.1	0.1	1	μF
3	R <sub>VDD</sub>	100	100	1000	Ω
4	Cvr	_	0.1	-	μF

**\*1.** Accuracy of overcharge detection voltage is guaranteed by typ. value in **Table 9**. Connecting components with other values will worsen the accuracy.

#### Caution

- 1. The constants may be changed without notice.
- 2. It has not been confirmed whether the operation is normal or not in circuits other than the connection examples. In addition, the connection examples and the constants do not guarantee proper operation. Perform thorough evaluation using the actual application to set the constants.
- 3. Set the same constants to R1 to R4 and to C1 to C4 and  $C_{VDD}$ .
- 4. Since the CO pin may become the detection status transiently when the battery is being connected, connect the positive terminal of BAT1 last in order to prevent the protection fuse from cutoff.

#### 2. 3-serial cell



\*1. This IC limits its CO pin output voltage to 7.5 V max., so a FET with the gate withstand voltage of 8 V can be used.

Figure 11

**Table 10 Constants for External Components** 

No.	Part	Min.	Typ.*1	Max.	Unit
1	R1 to R3	1	1	1	kΩ
2	C1 to C3, C <sub>VDD</sub>	0.1	0.1	1	μF
3	R <sub>VDD</sub>	100	100	1000	Ω
4	Cvr	ı	0.1	ı	μF

\*1. Accuracy of overcharge detection voltage is guaranteed by typ. value in **Table 10**. Connecting components with other values will worsen the accuracy.

#### Caution

- 1. The constants may be changed without notice.
- 2. It has not been confirmed whether the operation is normal or not in circuits other than the connection examples. In addition, the connection examples and the constants do not guarantee proper operation. Perform thorough evaluation using the actual application to set the constants.
- 3. Set the same constants to R1 to R3 and to C1 to C3 and  $C_{VDD}$ .
- Since the CO pin may become the detection status transiently when the battery is being connected, connect the positive terminal of BAT1 last in order to prevent the protection fuse from cutoff.

Rev.1.3\_00 S-82H4 Series

#### [For SCP, contact]

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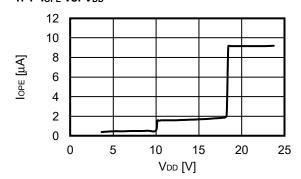
#### ■ Precaution

- Do not connect batteries charged with V<sub>CL</sub> or higher.
- If the connected batteries include a battery charged with V<sub>CL</sub> or higher, this IC may become the overcharge status after all pins are connected.
- In some application circuits, even if an overcharged battery is not included, the order of connecting batteries may be
  restricted to prevent transient output of the CO pin detection pulses when the batteries are connected. Perform
  thorough evaluation with the actual application circuit.
- Customers who desire a product that does not limit the order of battery connection should consider the S-82K3/K4 Series of products instead.
- Before the battery connection, short-circuit the battery side pins R<sub>VDD</sub> and R1, shown in the figures in "■ Battery Protection IC Connection Examples".
- The application conditions for the input voltage, output voltage, and load current should not exceed the power dissipation.
- Do not apply to this IC an electrostatic discharge that exceeds the performance ratings of the built-in electrostatic protection circuit.
- ABLIC Inc. claims no responsibility for any disputes arising out of or in connection with any infringement of patents owned by a third party by products including this IC.

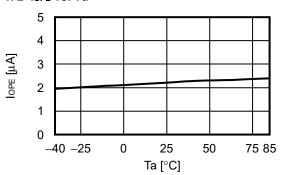
## ■ Characteristics (Typical Data)

#### 1. Current consumption

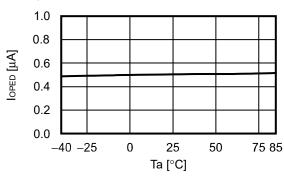
#### 1. 1 IOPE VS. VDD



1. 2 IOPE vs. Ta

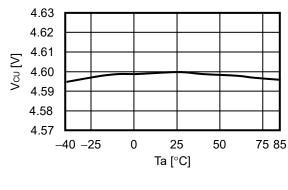


1. 3 loped vs. Ta

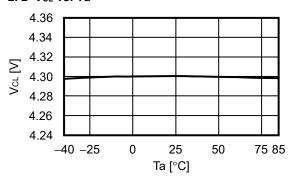


#### 2. Detection voltage, release voltage

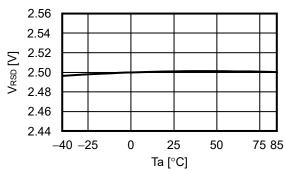
2. 1 V<sub>CU</sub> vs. Ta



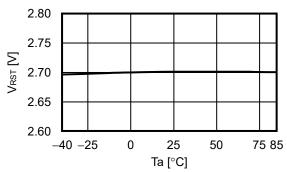
2. 2 V<sub>CL</sub> vs. Ta



2. 3 VRSD vs. Ta

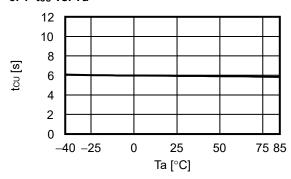


2. 4 V<sub>RST</sub> vs. Ta

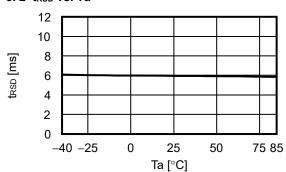


#### 3. Delay time

#### 3. 1 tcu vs. Ta

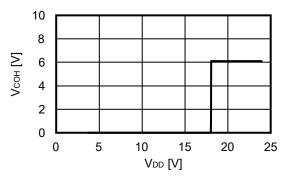


3. 2 t<sub>RSD</sub> vs. Ta

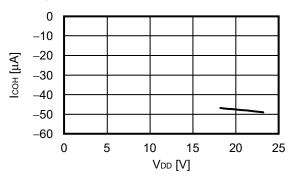


#### 4. Output pin

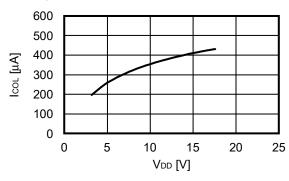
#### 4. 1 VCOH VS. VDD



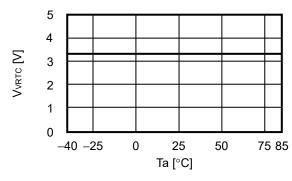
#### 4. 2 Icon vs. VDD



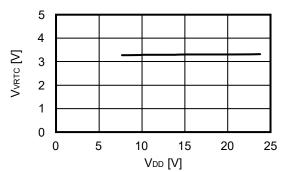
4. 3 Icol vs. VDD



4. 4 VVRTC VS. Ta

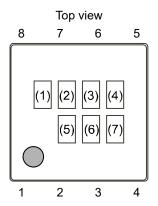


4. 5 VVRTC VS. VDD



## ■ Marking Specifications

#### 1. DFN-8(2020)A



(1): Blank

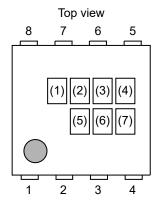
(2) to (4): Product code (Refer to **Product name vs. Product code**)

(5) to (7): Lot number

#### Product name vs. Product code

Due due tre energ	Product code				
Product name	(2)	(3)	(4)		
S-82H4AAA-A8T8U	9	K	Α		
S-82H4AAB-A8T8U	9	K	В		
S-82H4AAC-A8T8U	9	K	O		
S-82H4AAD-A8T8U	9	K	D		
S-82H4AAE-A8T8U	9	K	E		

#### 2. HSNT-8(1616)



(1): Blank

(2) ~ (4): Product code (Refer to **Product name vs. Product code**)

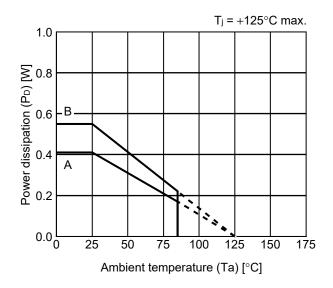
(5) ~ (7): Lot number

#### Product name vs. Product code

Due do et u eure	Product code			
Product name	(2) (3)		(4)	
S-82H4AAA-A8T2U	9	K	Α	

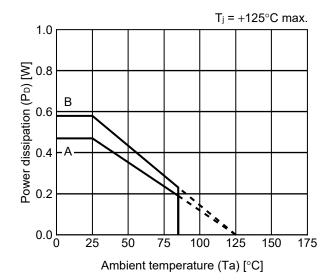
## **■** Power Dissipation

#### DFN-8(2020)A



Board	Power Dissipation (P <sub>D</sub> )	
Α	0.41 W	
В	0.55 W	
С	_	
D	_	
Е	_	

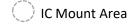
#### **HSNT-8(1616)**



Board	Power Dissipation (P <sub>D</sub> )	
А	0.47 W	
В	0.58 W	
С	_	
D	_	
Е	_	

# DFN-8(2020)A Test Board

## (1) Board A





Item		Specification
Size [mm]		114.3 x 76.2 x t1.6
Material		FR-4
Number of copper foil layer		2
Copper foil layer [mm]	1	Land pattern and wiring for testing: t0.070
	2	-
	3	-
	4	74.2 x 74.2 x t0.070
Thermal via		-

## (2) Board B



Item		Specification
Size [mm]		114.3 x 76.2 x t1.6
Material		FR-4
Number of copper foil layer		4
Copper foil layer [mm]	1	Land pattern and wiring for testing: t0.070
	2	74.2 x 74.2 x t0.035
	3	74.2 x 74.2 x t0.035
	4	74.2 x 74.2 x t0.070
Thermal via		-

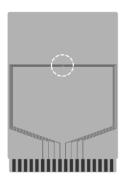


No. DFN8-E-Board-SD-1.0

# HSNT-8(1616) Test Board

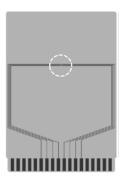
O IC Mount Area

## (1) Board A



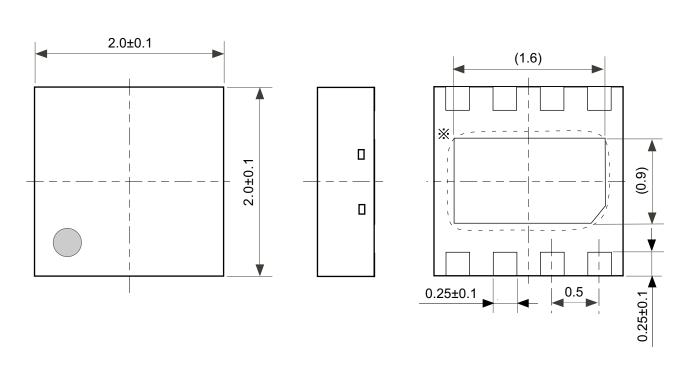
Item		Specification
Size [mm]		114.3 x 76.2 x t1.6
Material		FR-4
Number of copper foil layer		2
Copper foil layer [mm]	1	Land pattern and wiring for testing: t0.070
	2	-
	3	-
	4	74.2 x 74.2 x t0.070
Thermal via		-

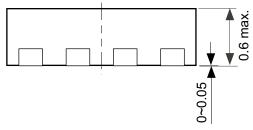
## (2) Board B



Item		Specification
Size [mm]		114.3 x 76.2 x t1.6
Material		FR-4
Number of copper foil layer		4
Copper foil layer [mm]	1	Land pattern and wiring for testing: t0.070
	2	74.2 x 74.2 x t0.035
	3	74.2 x 74.2 x t0.035
	4	74.2 x 74.2 x t0.070
Thermal via		-

No. HSNT8-B-Board-SD-1.0

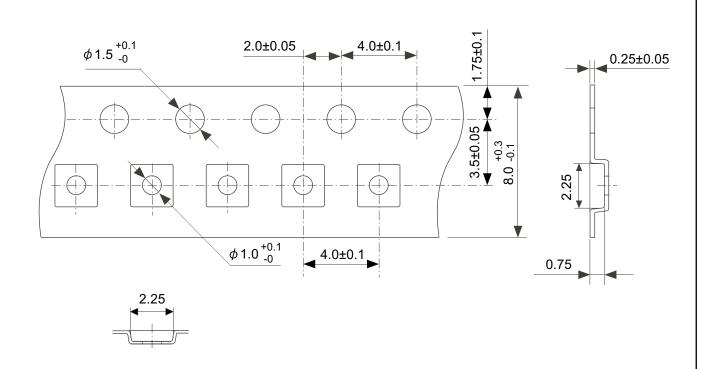


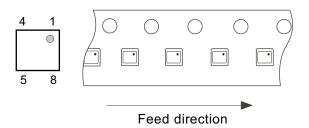


\*\* The heat sink of back side has different electric potential depending on the product. Confirm specifications of each product. Do not use it as the function of electrode.

#### No. IB008-A-P-SD-1.0

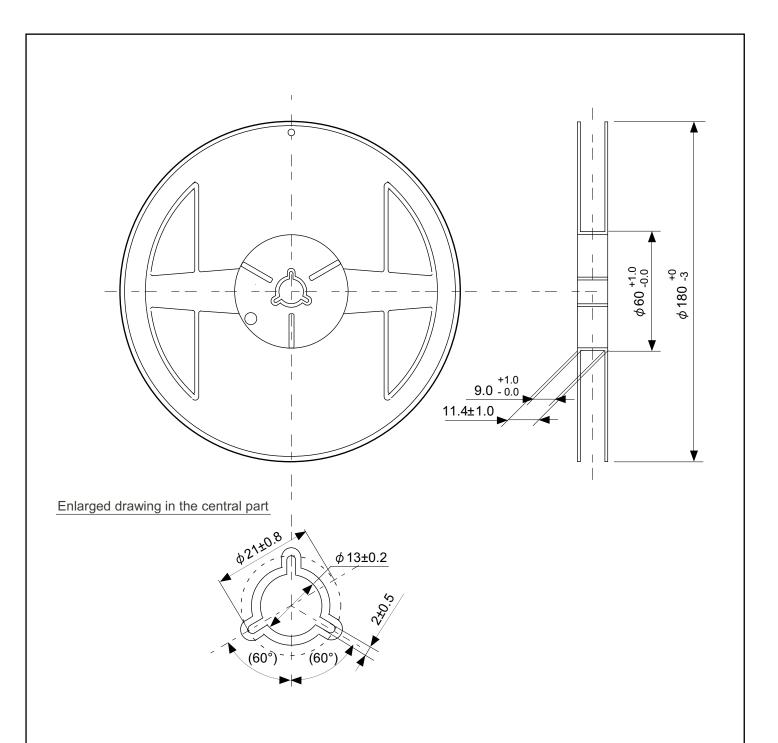
TITLE	DFN-8-E-PKG Dimensions	
No.	IB008-A-P-SD-1.0	
ANGLE	<b>\$</b>	
UNIT	mm	
ABLIC Inc.		





## No. IB008-A-C-SD-1.0

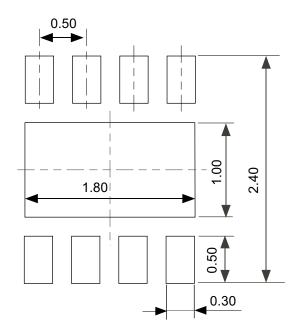
TITLE	DFN-8-E-Carrier Tape	
No.	IB008-A-C-SD-1.0	
ANGLE		
UNIT	mm	
ABLIC Inc.		



## No. IB008-A-R-SD-1.0

TITLE	DFN-8-E-Reel		
No.	IB008-A-R-SD-1.0		
ANGLE		QTY.	4,000
UNIT	mm		
ABLIC Inc.			

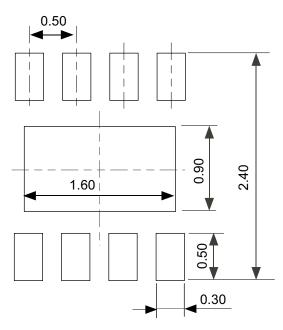
## **Land Pattern**



Cauion It is recommended to solder the heat sink to a board in order to ensure the heat radiation.

注意 放熱性を確保する為に、PKGの裏面放熱板(ヒートシンク)を基板に 半田付けする事を推奨いたします。

## Metal Mask Pattern



Caution ① Mask aperture ratio of the lead mounting part is 100%.

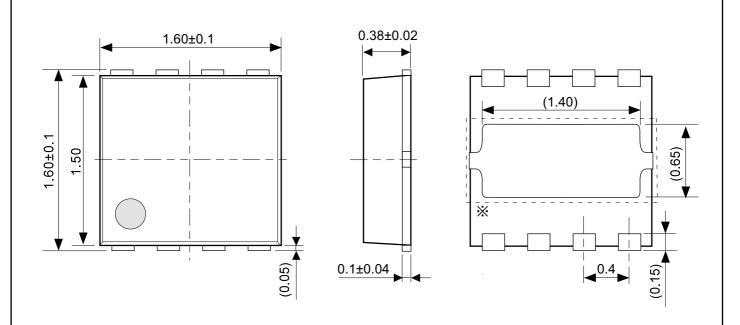
- 2 Mask aperture ratio of the heat sink mounting part is 80%.
- 3 Mask thickness: t0.12 mm

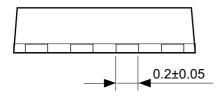
注意 ①リード実装部のマスク開口率は100%です。

- ②放熱板実装のマスク開口率は80%です。
- ③マスク厚み:t0.12 mm

No. IB008-A-L-SD-1.0

TITLE	DFN-8-E -Land Recommendation	
No.	IB008-A-L-SD-1.0	
ANGLE		
UNIT	mm	
	ABLIC Inc.	

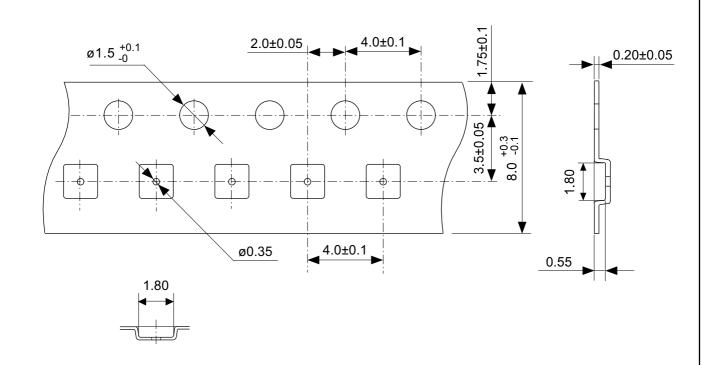


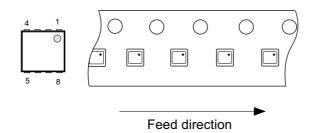


The heat sink of back side has different electric potential depending on the product.
 Confirm specifications of each product.
 Do not use it as the function of electrode.

## No. PY008-A-P-SD-1.0

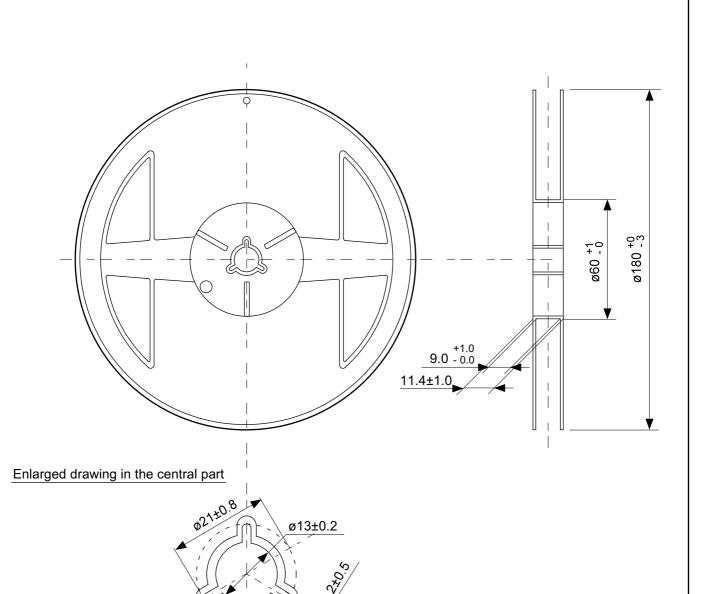
TITLE	HSNT-8-B-PKG Dimensions	
No.	PY008-A-P-SD-1.0	
ANGLE	<b>\$</b>	
UNIT	mm	
ABLIC Inc.		





## No. PY008-A-C-SD-1.0

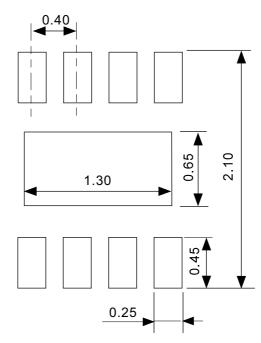
TITLE	HSNT-8-B-Carrier Tape		
No.	PY008-A-C-SD-1.0		
ANGLE			
UNIT	mm		
ABLIC Inc.			



## No. PY008-A-R-SD-1.0

TITLE	HSNT-8-B-Reel			
No.	PY008-A-R-SD-1.0			
ANGLE		QTY.	5,000	
UNIT	mm			
ABLIC Inc.				

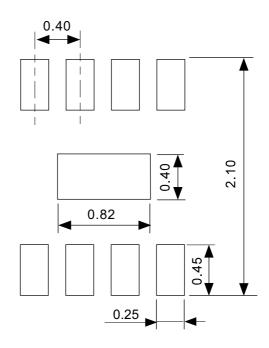
#### **Land Pattern**



Caution It is recommended to solder the heat sink to a board in order to ensure the heat radiation.

放熱性を確保する為に、PKGの裏面放熱板(ヒートシンク)を基板に 注意 半田付けする事を推奨いたします。

### Metal Mask Pattern



- Caution ① Mask aperture ratio of the lead mounting part is 100%.
  - 2 Mask aperture ratio of the heat sink mounting part is 40%.
  - 3 Mask thickness: t0.12 mm

注意 ①リード実装部のマスク開口率は100%です。

- ②放熱板実装のマスク開口率は40%です。
- ③マスク厚み:t0.12 mm

UNII	

No. PY008-A-L-SD-1.0

TITLE	-Land Recommendation	
No.	PY008-A-L-SD-1.0	
ANGLE		
UNIT	mm	
ABLIC Inc.		

HSNT-8-B

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